

ABSTRACT OF THE DISCLOSURE

There is provided a electronic parts packaging structure that includes a mounted body on which an electronic parts is mounted, the electronic parts having a connection pad, which has an etching stopper film (a copper film, a gold film, a silver film, or a conductive past film) as an uppermost film, and mounted on the mounted body to direct the connection pad upward, an interlayer insulating film for covering the electronic parts, a via hole formed in the insulating film on the connection pad of the electronic parts, and a wiring pattern connected to the connection pad via the via hole.